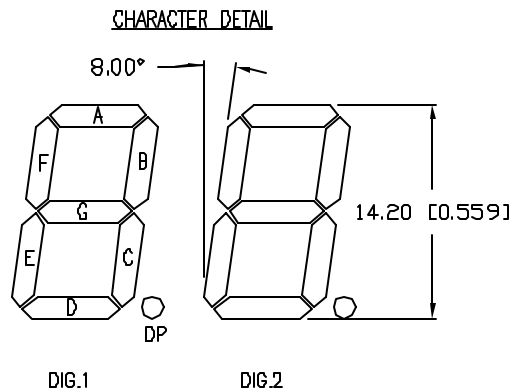
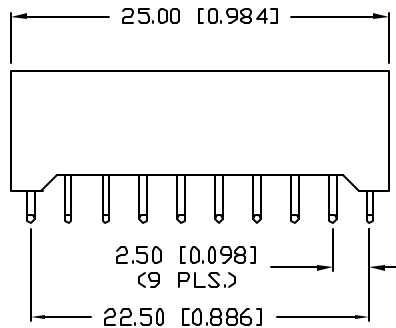
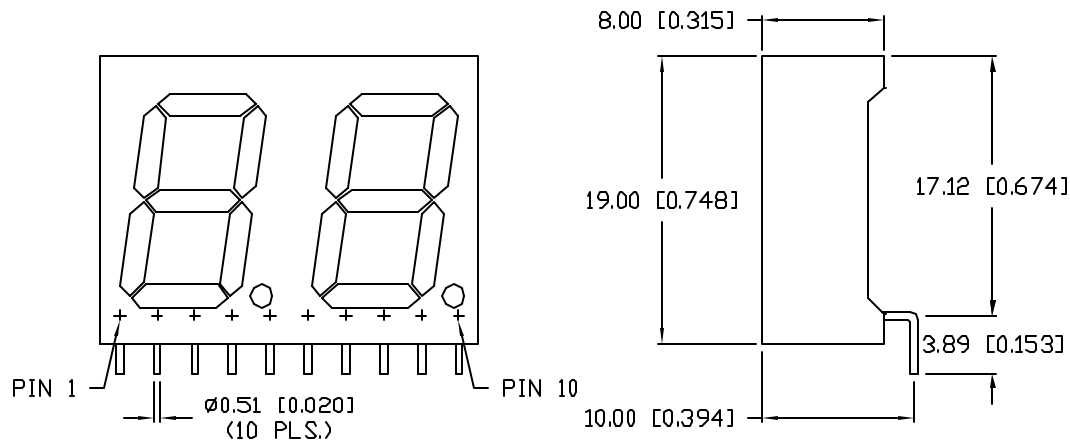


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| | | |
|-----------------|-------------------------------------|---------|
| (X) PART NUMBER | | REV. |
| LDD-M513RI-RA | | B |
| REV. | E.C.N. NUMBER AND REVISION COMMENTS | DATE |
| A | E.C.N. #10156. | 4-26-96 |
| B | E.C.N. #10BRDR. & REDRAWN. | 2-17-99 |



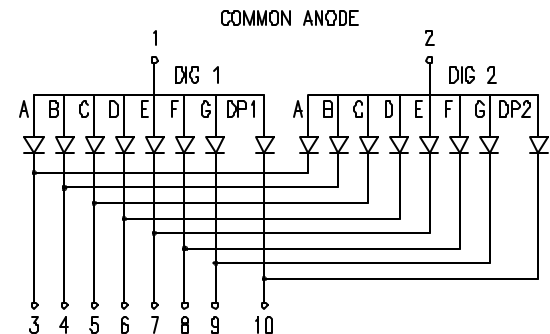
ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^{\circ}\text{C}$ $I_f=10\text{mA}$

| PARAMETER | MIN | TYP | MAX | UNITS | TEST COND |
|-----------------|----------------------|--------------|-----|----------------|-----------------------|
| PEAK WAVELENGTH | | 585 (YELLOW) | | nm | |
| FORWARD VOLTAGE | | 2.1 | 2.5 | V _f | |
| REVERSE VOLTAGE | 5.0 | | | V _r | I _r =100μA |
| AXIAL INTENSITY | | 3900 | | μcd | I _f =10mA |
| EMITTED COLOR: | YELLOW | | | | |
| FACE COLOR: | GRAY | | | | |
| SEGMENT COLOR: | MILKY WHITE DIFFUSED | | | | |

LIMITS OF SAFE OPERATION AT 25°C PER CHIP

| PARAMETER | MAX | UNITS |
|--------------------------|------------|------------|
| PEAK FORWARD CURRENT* | 150 | mA |
| STEADY CURRENT | 30 | mA |
| POWER DISSIPATION | 105 | mW |
| DERATE FROM 25°C | -1.2 | mW/°C |
| OPERATING, STORAGE TEMP. | -40 TO +85 | °C |
| SOLDERING TEMP. | +260 | °C |
| 2.0mm FROM BODY | | 3 SEC. MAX |

* t < 10μs



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*UNLESS OTHERWISE SPECIFIED TOLERANCE IS ±0.25mm (±0.010")

| | |
|------|---------------|
| REV. | PART NUMBER |
| B | LDD-M513RI-RA |

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 PALATINE, ILLINOIS 60067
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 WEB: HTTP://WWW.LUMEX.COM

0.56" SEVEN SEGMENT, DUAL DIGIT DISPLAY,
 585nm YELLOW CHIPS, GRAY FACE WITH WHITE SEGMENTS,
 COMMON ANODE, RIGHT DECIMAL PLACES, RIGHT ANGLE LEADS.

RELIABILITY NOTE
 OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

| | | | |
|-----------|-------------|--------------|---------------|
| DRAWN BY: | CHECKED BY: | APPROVED BY: | DATE: 1-30-96 |
| BC | | | PAGE: 1 OF 1 |
| | | | SCALE: N/A |